

<p>O.I.P.E.</p> <p>SCANNED <i>[Signature]</i> Q.A. <i>[Signature]</i></p>	<p>PATENT DATE</p>
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APPLICATION NO. 09/888642	CONT/PRIOR F	CLASS 205	SUBCLASS 17.5	ART UNIT 1743	EXAMINER S. H. Nicks
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Electric copper plating liquid and process for manufacturing semiconductor integrated circuit device using same

PTO-2040
12/99[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____			NOTICE OF ALLOWANCE MAILED	
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